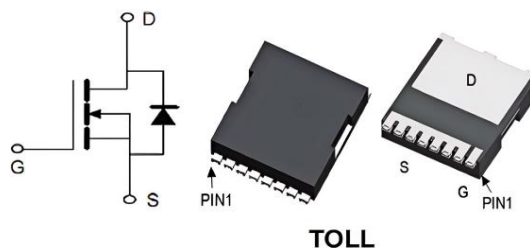


N-Channel Power MOSFET 100V/371A

Parameter	Value	Unit
VDS	100	V
RDS(on)	1.05	mΩ
ID	371	A



FEATURES

- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested

APPLICATIONS

- Load Switch
- PWM Application
- Power Management

MAXIMUM RATED VALUES

Symbol	Parameter		Rating	Unit
Common Ratings (T _c =25°C Unless Otherwise Noted)				
V(BR)DSS	Drain-Source Breakdown Voltage		100	V
VGS	Gate-Source Voltage		±20	V
T _j	Maximum Junction Temperature		150	°C
T _{stg}	Storage Temperature Range		-55 to 150	°C
IS	Diode Continuous Forward Current	TC=25°C	298	A
Mounted on Large Heat Sink				
EAS	Single Pulse Avalanche Energy (Note1)		2600	mJ
IDM	Pulse Drain Current Tested (Note2)	TC=25°C	1300	A
ID	Continuous Drain current(Silicon limit)	TC=25°C	371	A
PD	Maximum Power Dissipation	TC=25°C	357	W
RθJC	Thermal Resistance Junction-to-Case,		0.35	°C/W

ELECTRICAL CHARACTERISTICS (at T_J = 25°C unless otherwise specified)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_J= 25°C (unless otherwise stated)						
V(BR)DSS	Drain- Source Breakdown Voltage	VGS=0V, ID=250μA	100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA

VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	2	--	4	V
RDS(on)	Drain-Source On-State Resistance (Note3)	VGS=10V, ID=50A	--	1.05	1.2	mΩ
Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated) (Note4)						
Ciss	Input Capacitance	VDS=50V, VGS=0V, f=1MHz	--	12200	--	pF
Coss	Output Capacitance		--	4850	--	pF
Crss	Reverse Transfer Capacitance		--	96	--	pF
Qg	Total Gate Charge	VDS=50V ID=50A VGS=10V	--	199	--	nC
Qgs	Gate-Source Charge		--	60	--	nC
Qgd	Gate-Drain Charge		--	52	--	nC
RG	Reverse Transfer Capacitance	f=1MHz	--	4.5	--	Ω
Switching Characteristics (Note4)						
td(on)	Turn-on Delay Time	VDS=50V, ID=50A, RG=3Ω, VGS=10V	--	38	--	ns
tr	Turn-on Rise Time		--	63	--	ns
td(off)	Turn-off Delay Time		--	144	--	ns
tf	Turn-off Fall Time		--	84	--	ns
Source- Drain Diode Characteristics@ TJ = 25°C (unless otherwise stated)						
VSD	Forward on Voltage	IS=75A,VGS=0V,	--	--	1.2	V

Note:

1. Limited by TJ max, starting TJ = 25° C, RG = 25Ω, VD =50V, VGS =10V. Part not recommended for use above this value.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. Pulse Test: pulse width ≤ 300 us, duty cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

CHARACTERISTICS DIAGRAMS

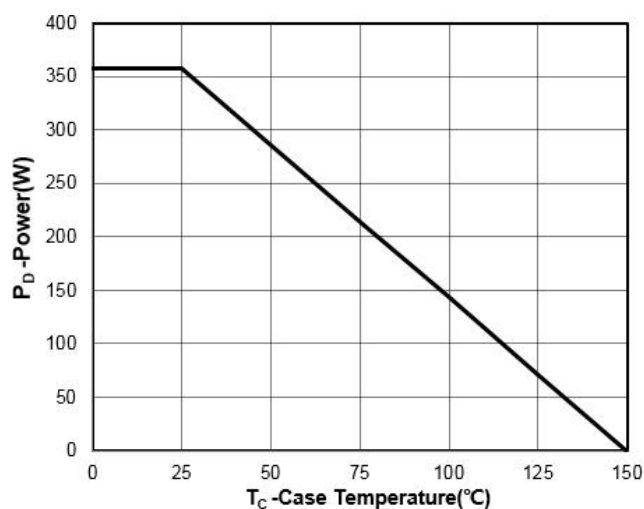


Figure1: Power De-rating

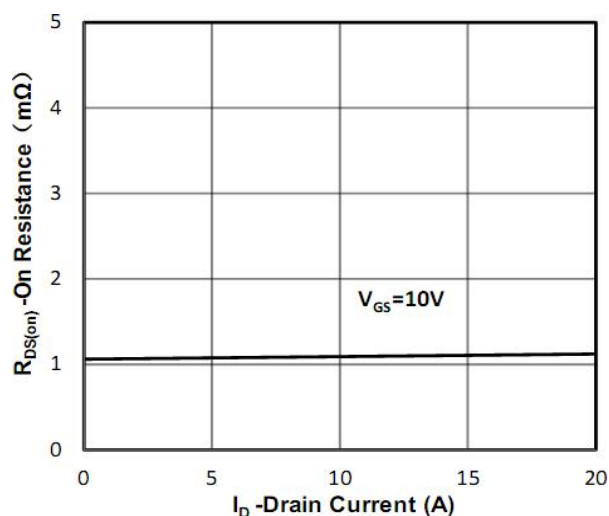


Figure2: RDS(on)-Drain Current

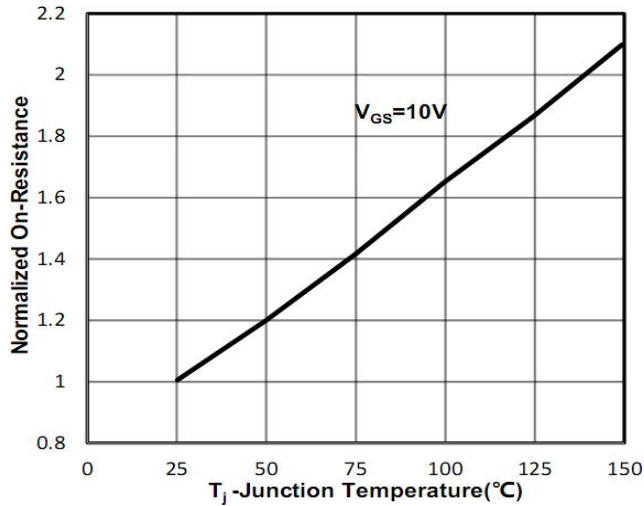


Figure3: $R_{DS(on)}$ -Junction Temperature

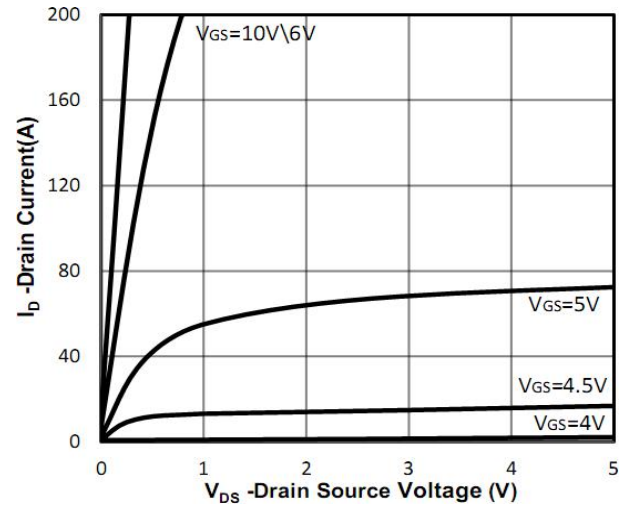


Figure4: Output Characteristics

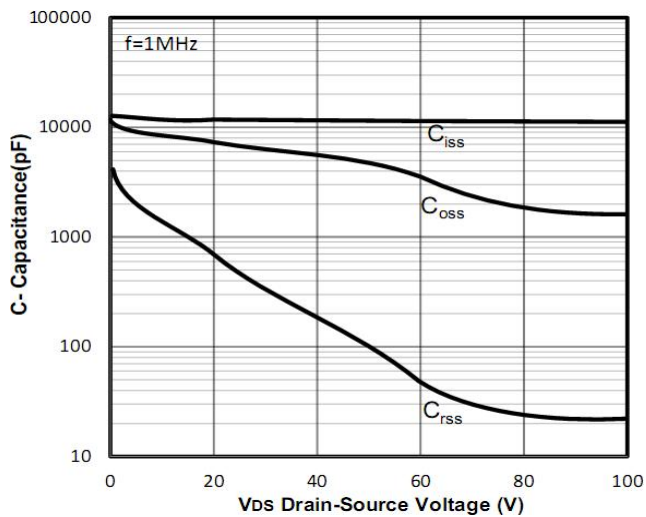


Figure5: Capacitance - V_{DS}

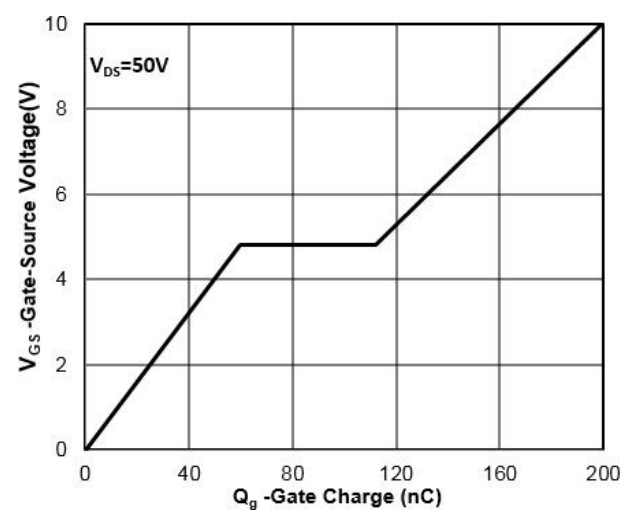


Figure6: Gate Charge

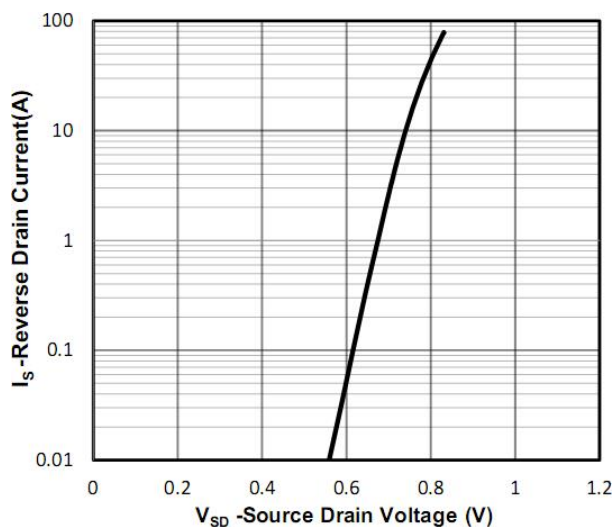


Figure7: Source-Drain Diode Forward

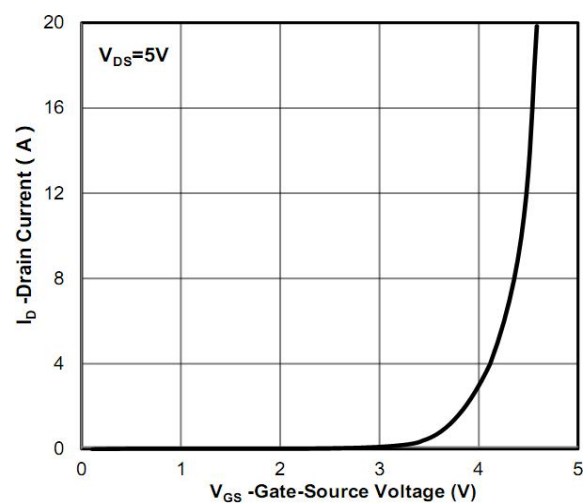


Figure8: Transfer Characteristics

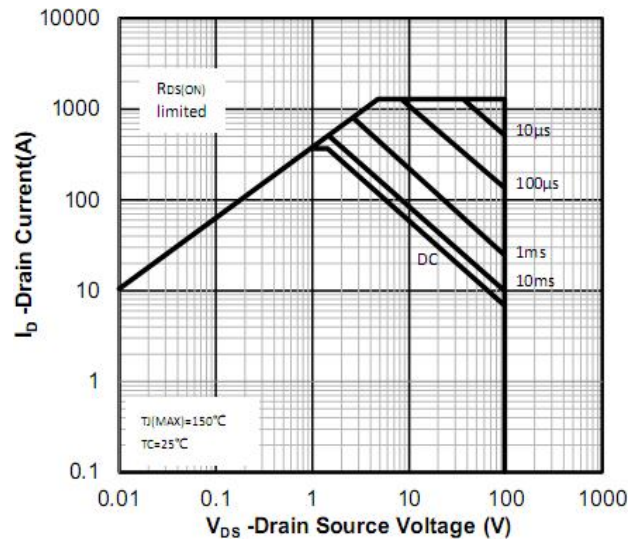


Figure9: Safe Operation Area

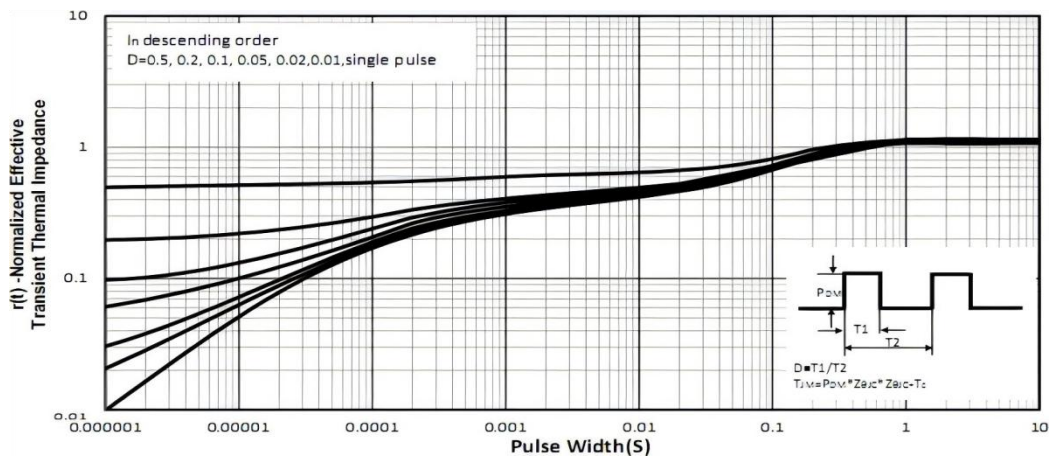
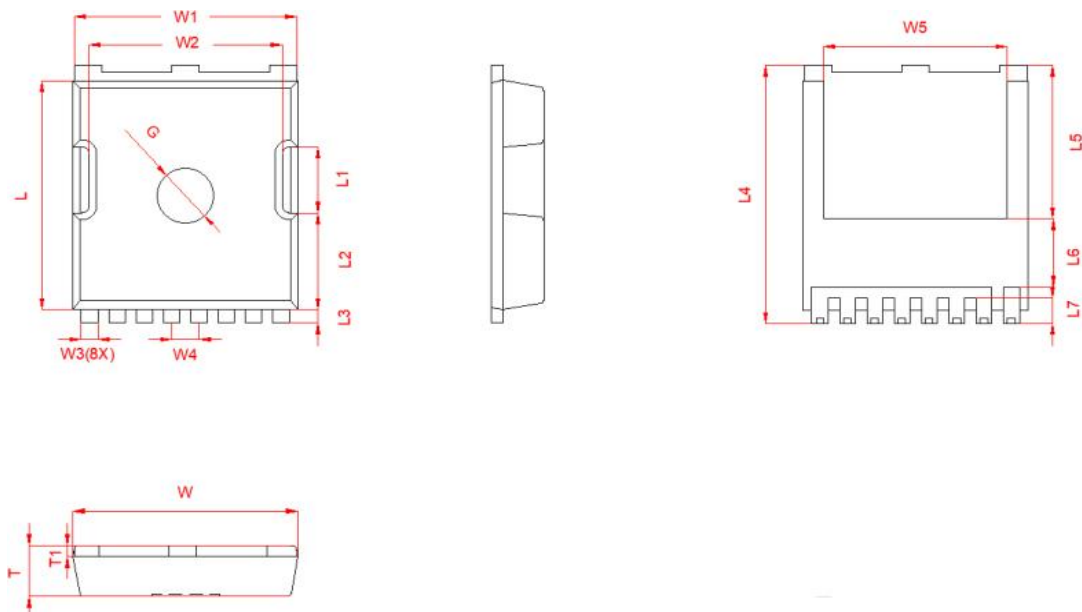


Figure10: Normalized Maximum Transient Thermal Impedance

PACKAGE OUTLINE



Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max
W	9.7	10.1	L	10.28	10.58	L6	(3.1)	
W1	9.7	9.9	L1	(3.0)		L7	1.1	1.3
W2	(8.5)		L2	4.2	4.6	T	2.2	2.4
W3	0.6	0.85	L3	0.5	0.7	T1	0.4	0.6
W4	1.1	1.3	L4	11.48	11.88	G(Φ)	(2.5)	
W5	(8.1)		L5	(6.9)				

*Important Usage Information and Disclaimer

The specifications of Zhuhai Hypersemi Co., Ltd. products are not guarantees of product characteristics. They reflect typical performance expected in standard applications, which may vary with specific uses. Users must conduct prior testing for their applications and make necessary adjustments.

Users are responsible for the safety of applications utilizing our products and must implement adequate safety measures to prevent physical injury, fire, or other risks in case of product failure. It is the user's duty to ensure that application designs comply with all applicable laws and standards. Our products must not be used in any applications where a product failure could reasonably result in personal injury, unless specifically authorized in a signed document by Zhuhai Hypersemi Co., Ltd.

No representations or warranties are made regarding the accuracy or completeness of this information, including any claims of non-infringement of third-party intellectual property rights. Zhuhai Hypersemi Co., Ltd. assumes no liability for any applications or uses of its products and does not grant any licenses to its intellectual property rights or those of others. We also make no claims regarding non-infringement of third-party intellectual property rights that may arise from applications.

Due to technical requirements, our products may contain hazardous substances. For details, please contact your nearest sales office. This document replaces all previous information and may be updated. We reserve the right to make changes.